



Product Data Sheet

RMA-223-LF Rosin Mildly Activated Solder Paste

Product Description

- Exceptional print definition
- Long stencil life
- Wide process window
- Excellent wetting compatibility on most board finishes
- Low voiding
- Compatible with enclosed printing heads

Alloys

Hirsch Metals manufactures a low-oxide, spherical and uniformly sized powder. RMA-223-LF is available in the following alloys: Sn96.5/Ag3.5, Sn95/Ag5, and Sn95/Sb5 alloys.

Powder Distribution

Micron Size	Type	Pitch Requirements
75 - 45	Type-2	24mil & above
45 - 25	Type-3	16mil to 24 mil
38 - 20	Type-4	12mil to 16mil
25 - 15	Type-5	<12mil
15 - 5	Type-6	<8mil

Available Packaging

The following packaging options are available for stencil printing and dispensing applications: 250g and 500g jars; 250g and 600g cartridges; 650g ProFlow[®] cassettes; 35g and 100g syringes; 2,500g FreshMix[®] Kits.

Stencil Life

6-8 hrs. @ 30–45% RH & 22–25°C
~4 hrs. @ 45–70% RH & 22–25°C

Viscosity

Printing applications: 700 to 1,100Kcps +/-10%
Dispensing applications: 400Kcps +/-10%
Tested according to IPC-TM-650

Tack Value

Typical tackiness: 34g force

Printing

The print definition of RMA-223-LF is ideal for fine pitch applications. The stencil life of this water-soluble product virtually eliminates waste of solder paste. Consult the powder distribution chart to determine your mesh size requirements.

Printer Operation

The following are general guidelines for stencil printer optimization with RMA-223-LF. Some adjustments may be necessary based on your process requirements.

Print Speed: 25–100mm/sec

Squeegee Pressure: 0.2–0.7kg/inch of blade

Under Stencil Wipe: Once every 10–25 prints or as necessary

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using 99% isopropyl alcohol (IPA) works well.

Storage and Handling Procedures

Refrigerated storage at 42–47°F will prolong the solder paste shelf life to no less than 6 months. Syringes & cartridges should be stored vertically with the dispensing tip down. Solder paste should be allowed to reach ambient temperature naturally, prior to use (about 6-8 hours). NEVER FREEZE SOLDER PASTE.

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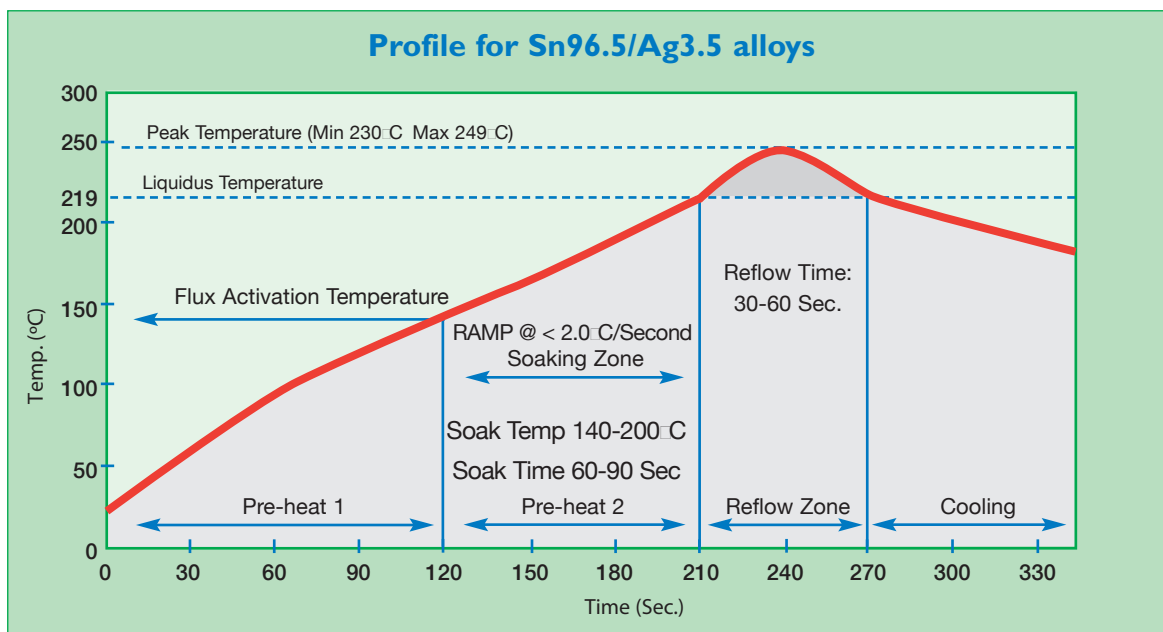
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J-STD-004 (IPC-TM-650) Test Results

Test	Standard	Values	Results
Flux Designator	IPC-TM-650 2.3.35	NA	ROM1

Recommended Profile:

This profile was designed to serve as a starting point for process optimization using RMA-223-LF. A cool down rate of (-) 2–4°C/second is ideal for the formation of a fine grain structure without risking damage to thermally sensitive components.



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